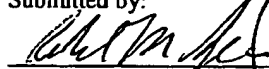


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2841 *2841***U.S. PATENT DOCUMENTS**

Exam. Init.	Document Number	Date	Name	Class	Sub Class	Filing Date (if approp.)
<i>DN</i>	2001/026957	04-10-2001	Atwood et al.			
	6504723	07-01-2003	Fitzgerald et al.			
	2003/134454	17-07-2003	Houle			
	5396403	07-03-1995	Patel et al.			
	4034468	12-07-1977	Koopman			
	6307749	23-10-2001	Daanen et al.			
<i>DN</i>	6504242	07-01-2003	Deppisch et al.			

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	Document Number	Date	Country	Class	Subclass	Translation Yes No
<i>DN</i>	0219424	07-03-2002	WO			Yes
	0981159	23-02-2000	EP			No
	19722357	19-11-1998	DE			No
<i>DN</i>	61014096	22-01-1986	JP			Abstract Only

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>DN</i>	MASSALSKI T B: "Binary Alloy Phase Diagrams" BINARY ALLOY PHASE DIAGRAMS. AC-AU to FE-RH, OHIO, AMERICAN SOCIETY FOR METALS, US, vol. VOL. 1, 1986, Pages 268, 270-271, XP002177614 *Page 270*
<i>DN</i>	SHIMIZU K et al.: "SOLDER JOINT RELIABILITY OF INDIUM-ALLOY INTERCONNECTION" JOURNAL OF ELECTRONIC MATERIALS, WARRENDAL, PA, US, vol. 24, no. 1, January 1995 (1995-01), Pages 39-45, XP000853947, *column 9, paragraph 2-column 10* *Figures 13, 14*
<i>DN</i>	CHEN Y - C et al.: "A fluxless bonding technology using indium-silver multilayer composites" IEEE TRANSACTIONS ON COMPONENTS, PACKAGING, AND MANUFACTURING TECHNOLOGY, PART A IEEE USA, vol. 20, no. 1, March 1997 (1997-03), pages 46-51, XP002369584, ISSN: 1070-9886 *figure 1*

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